	产	┗品规	格	承	人-	书		
	SF	PECIF	FICA	TI	0	IS		
客户:								
CUSTOMER: _								
产品名称:								
DESCRIPTION	l:	Bi	polar a	nter	nna			
客户型号:								
CUSTOMER MC	DEL No:							
产品型号:								
PRODUCT MOD	EL No: _]	PBX3216M	IP01				
日期: DATE:								
WITH YOUR A				1		TION FOR APPI		L
Approved	LiuFei	Audit	LiuFei	Mak	ing	LiuXiaoMei		
Customer A	Customer Acknowledges Signature							
	Date							
UNLESS OTHER SPECIF X=± X.X=± A N G L E S = ±	IED TOLER X.XX= H O L E D I		репоралих		深圳	市朋伴兴业科	技有	限公司
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TTLE: CHIP2450-3216 S	pecification	1	DOCUM NO.			3216		SPEC REV.

P1

PBX3216MP01 Specification

Operating Temp. : -40 ℃~+85 ℃

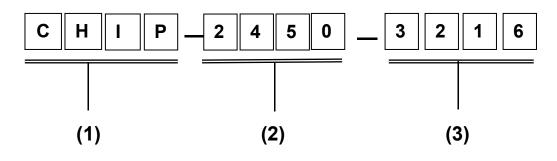
1. FEATURES:

- Light weight, compact
- Wide bandwidth, low cost
- Built-in antenna with high gain

2. APPLICATIONS:

- Bluetooth, Wireless LAN, Mobile TV
- Home RF System, etc

3. PRODUCT IDENTIFICATION



- (1) Product type: Multilayer chip Antenna
- (2) Center Frequency: 2450MHz
- (3) External Dimensions (L×W) (mm): 3.2*1.6

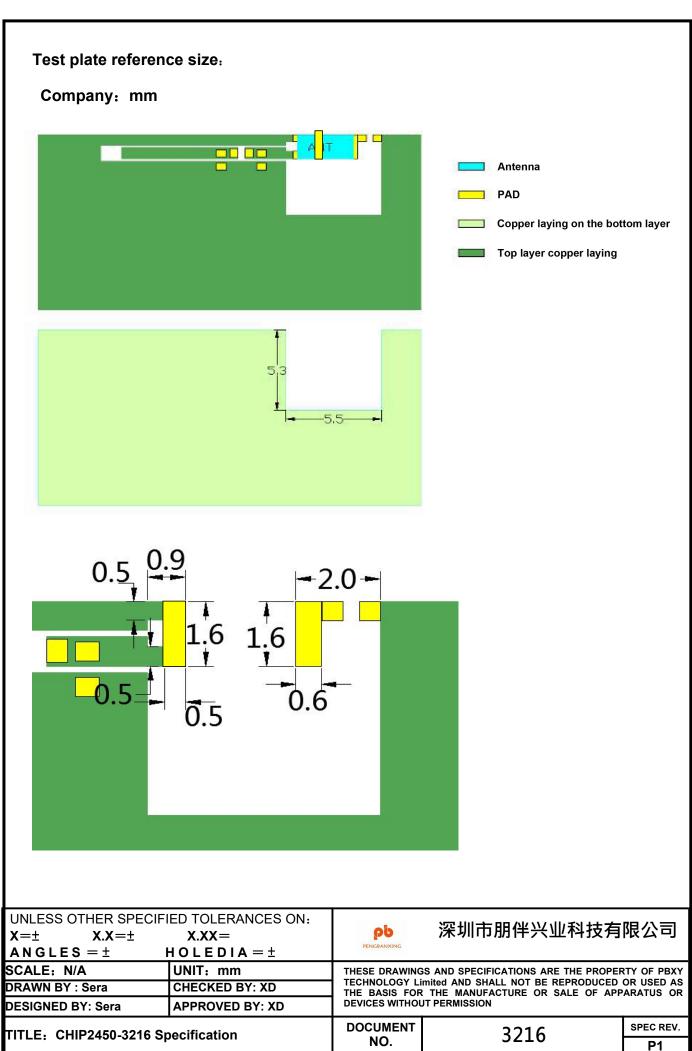
4. SHAPE AND DIMENSIONS:

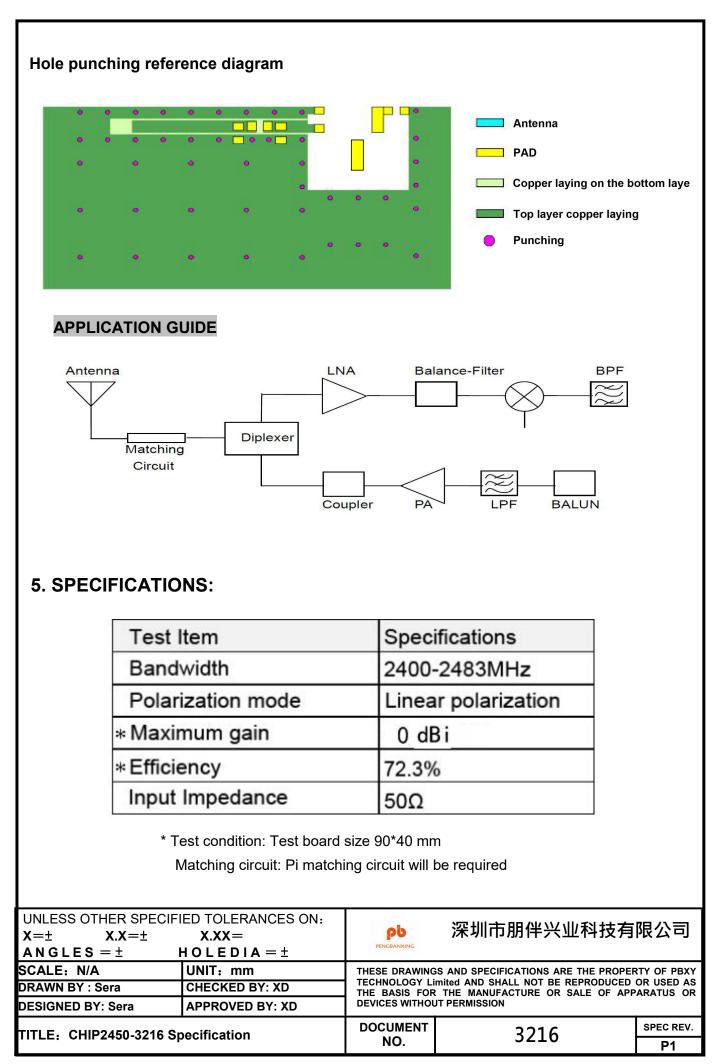


L	W	Н	А
3.2 ± 0.2	1.6 ± 0.2	0.52 ± 0.1	0.4 ± 0.1

н

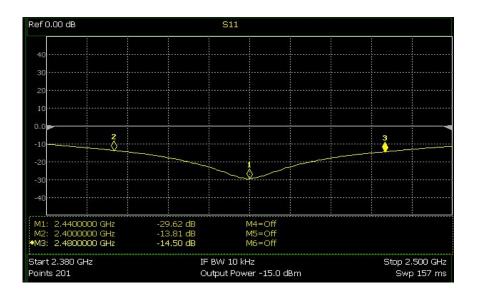
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SCALE: N/A UNIT: mm		THESE DRAWINGS AND SPECIFICATIONS ARE THE PROPERTY OF PBXY TECHNOLOGY Limited AND SHALL NOT BE REPRODUCED OR USED AS THE BASIS FOR THE MANUFACTURE OR SALE OF APPARATUS OR			
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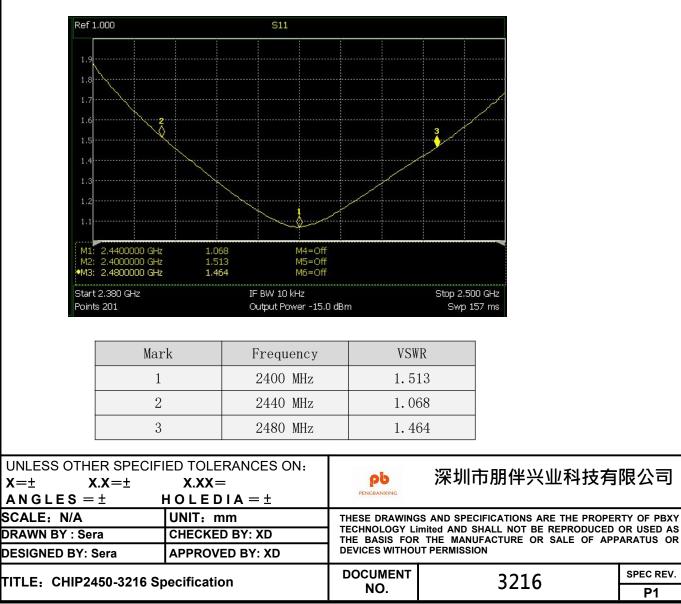




Return loss

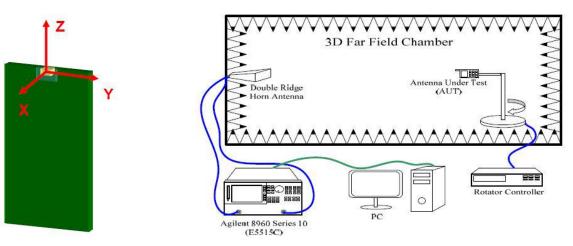


Standing wave ratio

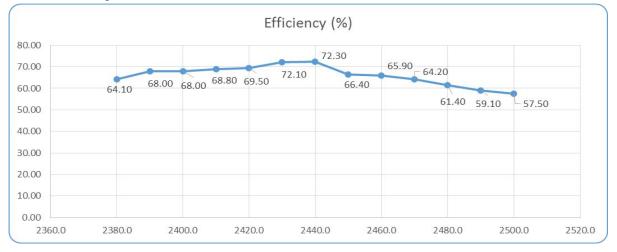


Radiation Pattern

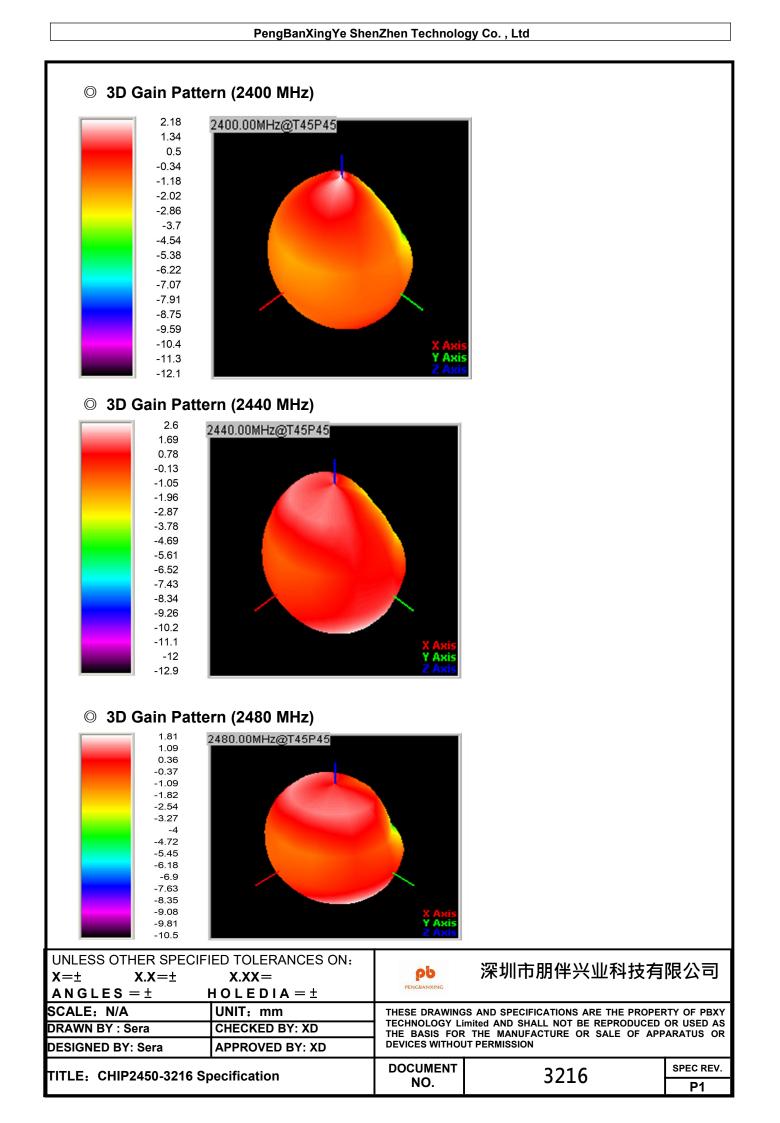
The Gain pattern is measured in FAR-field chamber. DUT is placed on the table of rotator, a standard horn antenna and Vector Network Analyzer is used to collect data.



◎ Efficiency



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7. Environmental Characteristics

(1) Reliability Test

Item	Condition	Specification
Thermal shock	1. 30 ± 3 minutes at $-40^{\circ} \text{ C}\pm 5^{\circ} \text{ C}$, 2. Convert to $+105^{\circ} \text{ C}$ (5 minutes) 3. 30 ± 3 minutes at $+105^{\circ} \text{ C}\pm 5^{\circ} \text{ C}$, 4. Convert to -40° C (5 minutes) 5. Total 100 continuous cycles	No apparent damage Fulfill the electrical spec. after test.
Humidity resistance	1. Humidity: 85% R.H. 2. Temperature: $85\pm5^{\circ}$ C 3. Time: 1000 hours.	No apparent damage Fulfill the electrical spec. after test.
High temperature resistance	1. Temperature: 150° C±5° C 2. Time: 1000 hours.	No apparent damage Fulfill the electrical spec. after test.
Low temperature resistance	1. Temperature: -40° C±5° C 2. Time: 1000 hours.	No apparent damage Fulfill the electrical spec. after test.
Soldering heat resistance	1. Solder bath temperature : 260±5℃ 2. Bathing time: 10±1 seconds	No apparent damage
Solderability	The dipped surface of the terminal shall be at least 95% covered with solder after dipped in solder bath of $245\pm5^\circ$ for 3 ± 1 seconds.	No apparent damage

(2) Storage Condition

(a) At warehouse:

The temperature should be within $0 \sim 30^{\circ}$ C and humidity should be less than 60% RH.

The product should be used within 1 year from the time of delivery.

(b) On board:

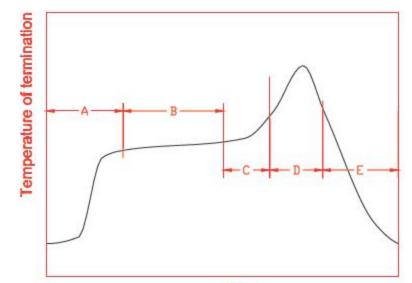
The temperature should be within -40~85°C and humidity should be less than 85% RH.

(3) Operating Temperature Range

Operating temperature range : -40 $^\circ\!\mathrm{C}$ to +105 $^\circ\!\mathrm{C}$.

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8. Recommended Reflow Soldering



		Time	
A	1 st rising temperature	The normal to Preheating temperature	30s to 60s
В	Preheating	140℃ to 160℃	60s to 120s
С	2 nd rising temperature	Preheating to 200°C	20s to 40s
	D Main heating	if 220°C	50s~60s
		if 230°C	40s~50s
D		if 240°C	30s~40s
		if 250°C	20s~40s
		if 260°C	20s~40s
E	Regular cooling	200°C to 100°C	$1^{\circ}C/s \sim 4^{\circ}C/s$
-	00.00		

*reference: J-STD-020C

(1) Soldering Gun Procedure

Note the follows, in case of using solder gun for replacement.

- (a) The tip temperature must be less than 350° C for the period within 3 seconds by using soldering gun under 30 W.
- (b) The soldering gun tip shall not touch this product directly.

(2) Soldering Volume

Note that excess of soldering volume will easily get crack the body of this product.

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(1) Quantity/Reel: 5000pcs/Reel

